

In the Claims:

Please cancel claims 12 and 13, without prejudice, and amend claims 11, 14 and 17 as follows:

1-10. (Cancelled)

11. (Currently Amended) A testing method for a head IC comprising:

a step of installing ~~a~~the head IC for processing an electric signal from a head for at least reading a disk medium, on a head suspension that supports said head; and

a step of placing ~~a probe~~probes on ~~a terminal~~terminals of said head suspension to check electric characteristics of said head ~~IC~~IC,

wherein said head suspension comprises:

a first connection terminal for electrically connecting to said head, on which is placed one of said probes;

a second connection terminal for connecting to external circuits;

third and fourth connection terminals for electrically connecting to said head IC;

a first conductive path that connects said first and third connection terminals;

a second conductive path that connects said second and fourth connection terminals; and

a measurement terminal that is located between said second connection terminal and said fourth connection terminal of said second conductive path, on which is placed one of said probes,

and wherein said measurement terminal and said first connection terminal are located on a first plane of said head suspension;

and said second connection terminal is located on a second plane of said head suspension that is substantially perpendicular to the first plane.

12. (Cancelled)

13. (Cancelled)

14. (Currently Amended) The testing method of claim 11 wherein; said first, second, third and fourth connection terminals, said first and second conductive paths, and said measurement terminal are formed using a thin-film pattern on ~~the~~ a base of said suspension.

15. (Currently Amended) The testing method of claim 11 further comprising:

a base for said head suspension; and

a flexible cable on which said first, second, third and fourth connection ~~terminal~~terminals, said first and second conductive paths and said measurement terminal are formed.

16. (Original) The testing method of claim 11 wherein said head comprises a magnetic head.

17. (Currently Amended) A ~~manufacturing~~testing method for a HGA ~~comprising: of claim 11 wherein said step of placing probes is executed before mounting the~~
head to said head suspension.

~~_____ a step for installing a head IC for processing an electric signal from a head for at least reading a disk medium, on a head suspension that supports said head;~~

~~_____ a step of placing a probe on a terminal of said head suspension to check electric characteristics of said head IC; and~~

~~_____ a step of installing a head on said head suspension with said head IC.~~